

Plenary Speech	Industrial / Special Session	Packaging Session	PCB Session	Poster Session
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Time	Wednesday October 25				Time	Thursday October 26				Time	Friday October 27			
	Room 504abc					Room 504ab					Room 504a			
10:00-10:20	IMPACT 2023 Opening & Awards Ceremony				09:00-10:30	IEEE EPS and CEDA Joint Panel_ Co-Design for AI				09:00-09:40	<Plenary Speech III>			
10:20-11:10	<Plenary Speech I>									09:40-10:20	Dr. Beth Keser, VP, Zero ASIC			
	Dr. Jun He, VP, TSMC				10:40-12:30	R504 a	R504 b	R504 c	R503	10:30-12:30	R504 a	R504 b	R504 c	R503
	<Plenary Speech II>					【S9】	【S10】	【S11】	【S12】		【S21】	【S22】	【S23】	【S24】
11:10-12:00	Dr. Raja Swaminathan,CVP, AMD					JIEP	Leading Advanced Packaging (SPIL)	Advanced Materials, Automatic Process & Bonding	Advanced Interconnection & Reliability		Market Trend : Innovative Packaging Technology Applied in AR/VR, AI, and ESG	Thermal Modeling & Characterization	High Speed Signal & Interconnect	Advanced PCB/Substrate & Soldering
12:00-13:30	Lunch				12:30-13:30	Lunch				12:30-13:30	Lunch			
13:30-15:30	R504a	R504b	R504c	R503	13:30-15:30	R504 a	R504 b	R504 c	R503	13:30-16:00	R504 a	R504 b	R504 c	R503
	【S1】	【S2】	【S3】	【S4】		【S13】	【S14】	【S15】	【S16】		【S25】	【S26】	【S27】	【S28】
	iNEMI	AI Creating a New ERA of Advanced packaging (MKS' Atotech)	Fan-out Packaging & Interconnection	Power Electronics		ICEP	Intel Data Center Modular Hardware System(Intel)	Advanced Packaging Material Modeling & Characterization	Advanced and Green Materials & Process		JIEP	Design, Modeling & Testing	Advanced Packaging & Material Characterization	HDI & FPC Technologies
15:30-15:50	Poster session (Packaging)				15:30-15:50	Poster session (PCB)								
15:50-17:50	【S5】	【S6】	【S7】	【S8】	15:50-17:50	【S17】	【S18】	【S19】	【S20】					
	3D Embedding	IAAC :Technology for Chiplets Interface (iMAPS Taiwan)	Advanced Packaging & Processing	Power Electronics		Heterogeneous Integration	AI-based Reliability Characterization & Prediction	Advanced Packaging Technologies	Test, Inspection & Characterization					
					18:15-20:30	IMPACT 2023 Welcome Dinner (by Invited)								